

Please amend the application identified above as follows:

IN THE CLAIMS

Please amend claim 1 as follows:

SUB
C17

B1

1. (Twice Amended) A semiconductor integrated circuit device comprising:
- a die connected to a ground lead and a power lead;
 - a ground plane connected to the ground lead, the ground plane enclosed within an encapsulating material;
 - an electrically insulating layer between said die and said ground plane; and
 - a decoupling capacitor having a first end and a second end, the first end connected to the ground lead and the second end connected to the power lead;
- wherein the encapsulating material encapsulates the die, the ground plane, the electrically insulating layer and the decoupling capacitor.

Please add the following new claims:

sub D1
B2

12. The semiconductor integrated circuit device according to Claim 1, wherein the ground plane comprises a layer of metal.
13. The semiconductor integrated circuit device according to Claim 12, wherein the layer of metal comprises copper.